

RESIN COMPOSITION AND SEMICONDUCTOR DEVICE PRODUCED USING RESIN COMPOSITION

[ABSTRACT]

A resin composition of the present invention includes a maleimide derivative (A) represented by a general formula (1) and a bis-maleimide compound (B) represented by a general formula (2). In the general formula (1), R1 represents a straight chain or branched alkylene group having 1 or more carbon atoms, R2 represents a straight chain or branched alkyl group having 5 or more carbon atoms, and the sum of carbon atoms of R1 and R2 is 10 or less. In the general formula (2), X1 represents -O-, -COO-, or -OCOO-, R3 represents a straight chain or branched alkylene group having 1 to 5 carbon atoms, R4 represents a straight chain or branched alkylene group having 3 to 6 carbon atoms, and m is an integer of 1 or more and 50 or less.



